

# MATERIAL DECLARATION SHEET



Material Number	CW2012A Series			
Product Line	Chip Inductor			
Compliance Date	2024/03/22			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic body	ALUMINA CORE	0.00684	Aluminum oxide	1344-28-1	97.207	73.877	76.00
				Silicon dioxide	14808-60-7	2.793	2.123	
2	Terminal	Ag-Pd LAYER	0.00027	Silver	7440-22-4	70.589	2.118	3.00
				Palladium	7440-05-3	23.529	0.706	
				Silica glass	60676-86-0	5.882	0.176	
3	Solder Base	Ni-PLATING	0.00009	Nickel	7440-02-0	100.000	1.000	1.00
4	Solder	Sn-PLATING	0.00009	Tin	7440-31-5	100.000	1.000	1.00
5	Copper/ Coating	Copper Wire	0.00130536	Copper	7440-50-8	100.000	14.504	15.00
		ELEKTRISOLA POLYURETHANE-BASED INSULATION VARNISH_P180	0.00004464	Polyurethane Resin	26680-22-8	100.000	0.496	
6	Back Membrane	UV Adhesive	0.00036	TRIPROPYLENE GLYCOL DIACRYLATE	42978-66-5	95.000	3.800	4.00
				HYDROXY CYCLOHEXYL PHENYL KETONE	947-19-3	5.000	0.200	
Total weight			0.009					

**This Document was updated on: 2024/03/26**

**Important remarks:**

- It is the responsibility of the user to verify they are accessing the latest version.